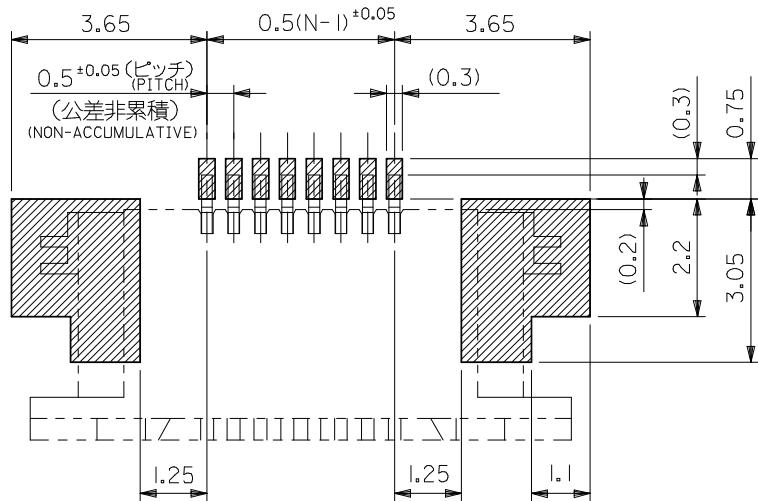


注記(NOTES)

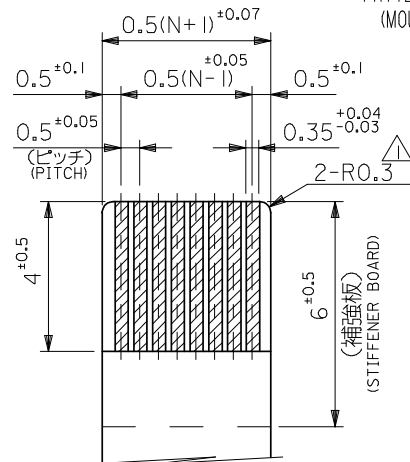
1. 使用材料 (MATERIAL)
 ターミナル (TERMINAL): リン青銅
 PHOSPHOR BRONZE t=0.2
 鍍ビスマスメッキ 1. 0マイクロメートル以上
 TIN-BISMUTH I.O. MICROMETER MINIMUM
 ニッケル下地 1. 0マイクロメートル以上
 NICKEL(UNDER PLATING)I.O. MICROMETER MINIMUM
 ハウジング (HOUSING): 46ナイロン(46NYLON), UL94V-0
 金具 (FITTING NAIL): リン青銅
 PHOSPHOR BRONZE t=0.2
 鍍メッキ 1. 0マイクロメートル以上
 TIN I.O. MICROMETER MINIMUM
 ニッケル下地 1. 0マイクロメートル以上
 NICKEL(UNDER PLATING)I.O. MICROMETER MINIMUM
2. パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB. PATTERN.)
3. ソルダテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 L に対し上方向 0.1MAX.、下方向 0.15MAX. とする。
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L
 UPPER DIRECTION 0.1MAX., LOWER DIRECTION 0.15MAX.
4. 偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)
5. 本製品は 52689-***40 の鉛フリー品である。
 THIS PRODUCT IS LEAD FREE 52689-***40.

REVISED EC NO: J2008-4308 DRWN:WABEI 2008/06/27 CHKD:THAYAMA 2008/06/30 APPR:NUKITA 2008/06/30 REV B	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY H. KAWABATA	DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE '04/02/03	MOLEX INCORPORATED			
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/02/03	DOCUMENT NO. SD-52689-034		SHEET NO. 1 OF 2	
	ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 2			

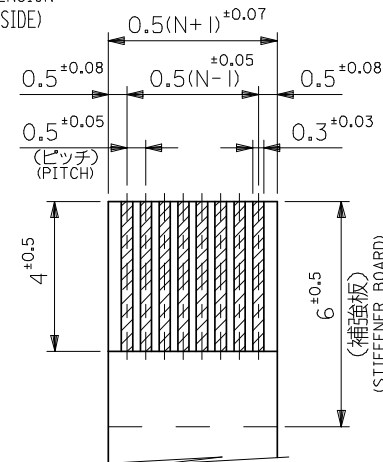


参考基板レイアウト
(マウント面)

REFERENCE P.C.BOARD
PATTERN DIMENSION
(MOUNTING SIDE)



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3 ± 0.03)
(THICKNESS: 0.3 ± 0.03)



適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3 ± 0.03)
(THICKNESS: 0.3 ± 0.03)

FPCについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION : FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

注記 NOTES

△ R0.3は、FPCの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

17.6	21.1	19.3	15.5	14.5	52689-3087	52689-3049	30
17.1	20.6	18.8	15.0	14.0	-2987	-2949	29
16.6	20.1	18.3	14.5	13.5	-2887	-2849	28
16.1	19.6	17.8	14.0	13.0	-2787	-2749	27
15.6	19.1	17.3	13.5	12.5	-2687	-2649	26
15.1	18.6	16.8	13.0	12.0	-2587	-2549	25
14.6	18.1	16.3	12.5	11.5	-2487	-2449	24
14.1	17.6	15.8	12.0	11.0	-2387	-2349	23
13.6	17.1	15.3	11.5	10.5	-2287	-2249	22
13.1	16.6	14.8	11.0	10.0	-2187	-2149	21
12.6	16.1	14.3	10.5	9.5	-2087	-2049	20
12.1	15.6	13.8	10.0	9.0	-1987	-1949	19
11.6	15.1	13.3	9.5	8.5	-1887	-1849	18
11.1	14.6	12.8	9.0	8.0	-1787	-1749	17
10.6	14.1	12.3	8.5	7.5	-1687	-1649	16
10.1	13.6	11.8	8.0	7.0	-1587	-1549	15
9.6	13.1	11.3	7.5	6.5	-1487	-1449	14
9.1	12.6	10.8	7.0	6.0	-1387	-1349	13
8.6	12.1	10.3	6.5	5.5	-1287	-1249	12
8.1	11.6	9.8	6.0	5.0	-1187	-1149	11
7.6	11.1	9.3	5.5	4.5	-1087	-1049	10
7.1	10.6	8.8	5.0	4.0	-0987	-0949	9
6.6	10.1	8.3	4.5	3.5	-0887	-0849	8
6.1	9.6	7.8	4.0	3.0	-0787	-0749	7
5.6	9.1	7.3	3.5	2.5	-0687	-0649	6
5.1	8.6	6.8	3.0	2.0	52689-0587	52689-0549	5

52689-***49	W	D	C	B	A	EMBOSSSED TAPE	MATERIAL NO.	極数 CKT.
MODEL NO.						ORDER No. オーダー番号		

REVISED EC NO: J2008-4308 DRWN:WABEI 2008/06/27 CHKD:THARUYAMA 2008/06/30 APPR:NUKITA 2008/06/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY H. KAWABATA	DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE '04/02/03	MOLEX INCORPORATED			
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/02/03	DOCUMENT NO. SD-52689-034			
	ANGULAR	±3 °	MATERIAL NO. SEE TABLE		SHEET NO. 2 OF 2			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						